

# BCW66

Rev.F Apr.-2017

## / Descriptions

SOT-23

NPN

Silicon NPN transistor in a SOT-23 Plastic Package.

## / Features

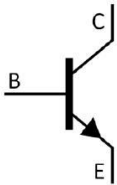
BCW68

Complementary to BCW68.

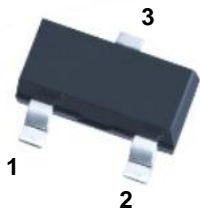
## / Applications

Medium power amplifier applications.

## / Equivalent Circuit



## / Pinning



PIN1 Base    PIN 2 Emitter    PIN 3 Collector

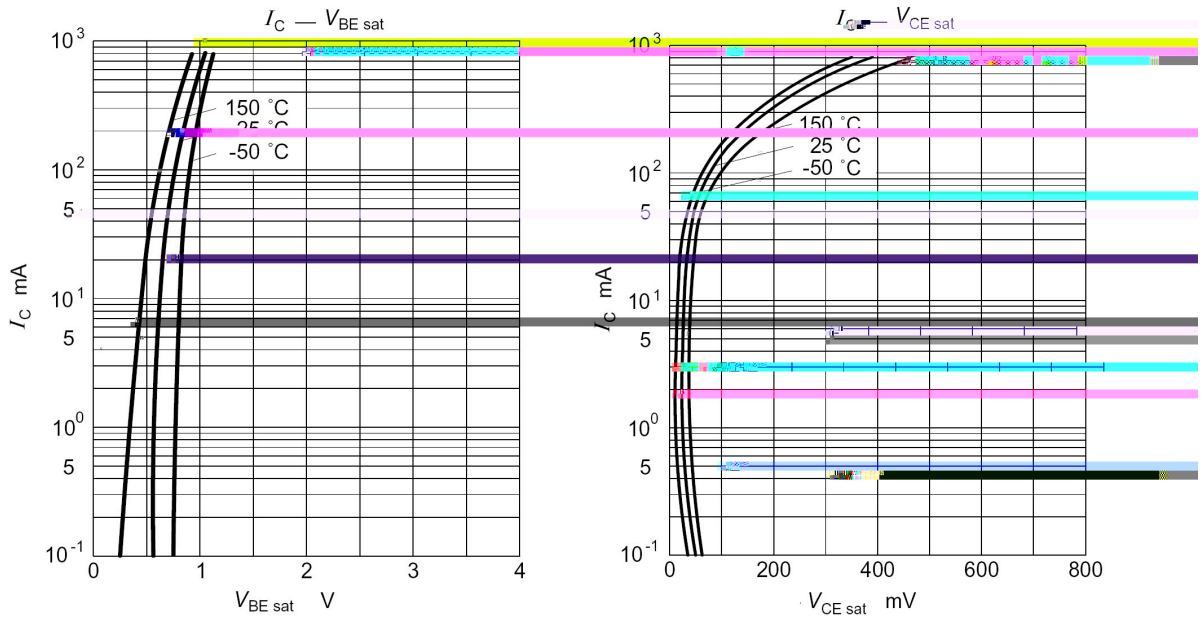
## / $h_{FE}$ Classifications & Marking

$h_{FE}$ Classifications Symbol	F	G	H
$h_{FE}$ Range	100 250	160 400	250 630
Marking	HDAO	HDAY	HDAG

Parameter	Symbol	Rating	Unit
Collector to Base Voltage	$V_{CBO}$	75	V
Collector to Emitter Voltage	$V_{CEO}$	45	V
Emitter to Base Voltage	$V_{EBO}$	5.0	V
Collector Current(DC)	$I_C$	800	mA
Peak Collector Current	$I_{CM}$	1.0	A
Peak Base Current	$I_B$	100	mA
Collector Power Dissipation	$P_C$	330	mW
Junction Temperature	$T_j$	150	
Storage Temperature Range	$T_{stg}$	-55 150	

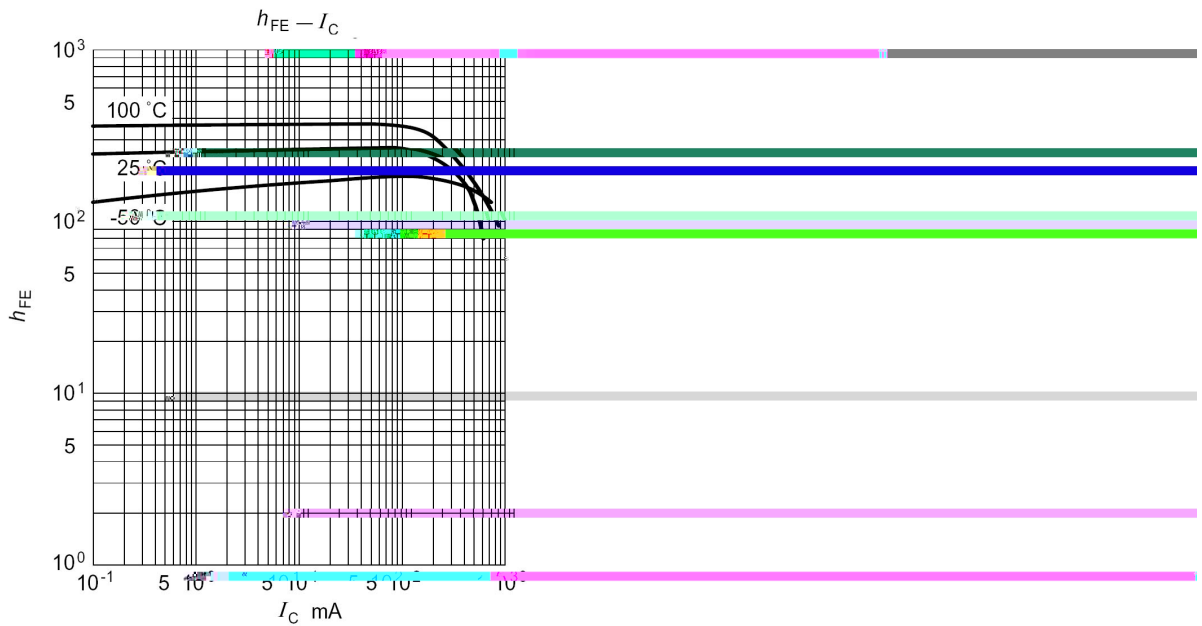
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Collector to Base Breakdown Voltage	$V_{CBO}$	$I_C=10\text{ A}$	75			V
Collector to Emitter Breakdown Voltage	$V_{CEO}$	$I_{CEO}=10\text{mA}$	45			V
Emitter to Base Breakdown Voltage	$V_{EBO}$	$I_{EBO}=10\text{ A}$	5.0			V
Collector-Emitter Cut-off Current	$I_{CES}$	$V_{CB}=45\text{ V}$			0.1	A
Emitter Base Cut-Off Current	$I_{EBO}$	$V_{EB}=4.0\text{V}$			0.1	A
DC Current Gain	$h_{FE(1)}$	$V_{CE}=1.0\text{V}$ $I_C=100\text{mA}$	100		630	
	$h_{FE(2)}$	$V_{CE}=1.0\text{V}$ $I_C=10\text{mA}$	75			
	$h_{FE(3)}$	$V_{CE}=2.0\text{V}$ $I_C=500\text{mA}$	35			
Collector to Emitter Saturation Voltage	$V_{CE(sat)(1)}$	$I_C=100\text{mA}$ $I_B=10\text{mA}$			0.3	V
	$V_{CE(sat)(2)}$	$I_C=500\text{mA}$ $I_B=50\text{mA}$			0.7	V
Base to Emitter Saturation Voltage	$V_{BE(sat)}$	$I_C=500\text{mA}$ $I_B=50\text{mA}$			2.0	V

**/ Electrical Characteristic Curve**

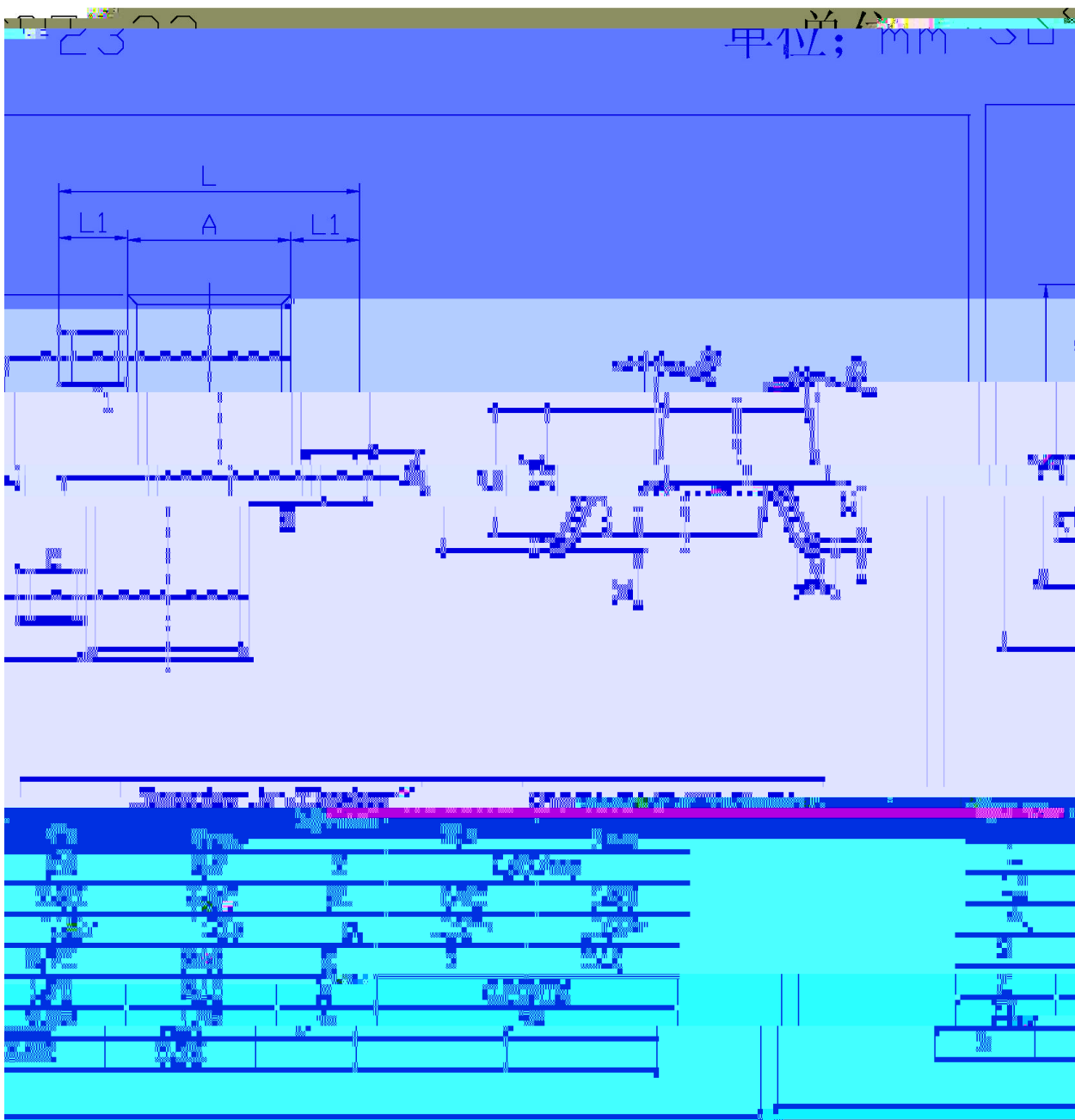


**DC current gain  $h_{FE} = f(I_C)$**

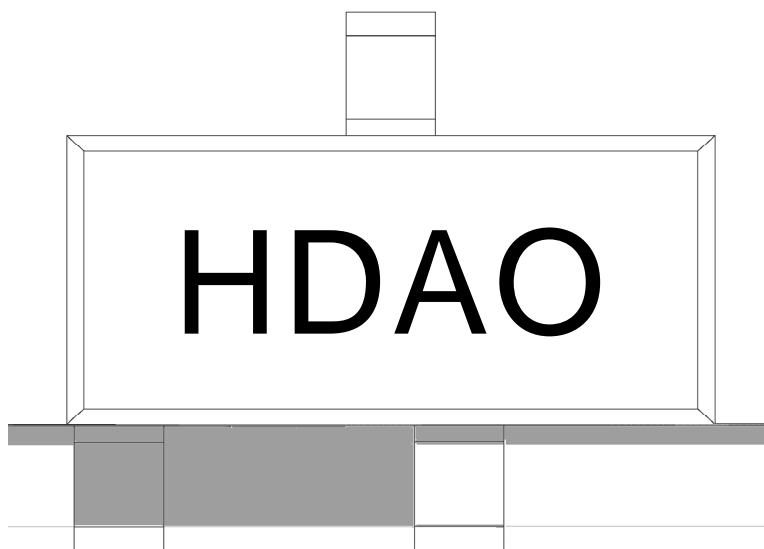
$V_{CE} = 1V$



/ Package Dimensions



/ Marking Instructions



H

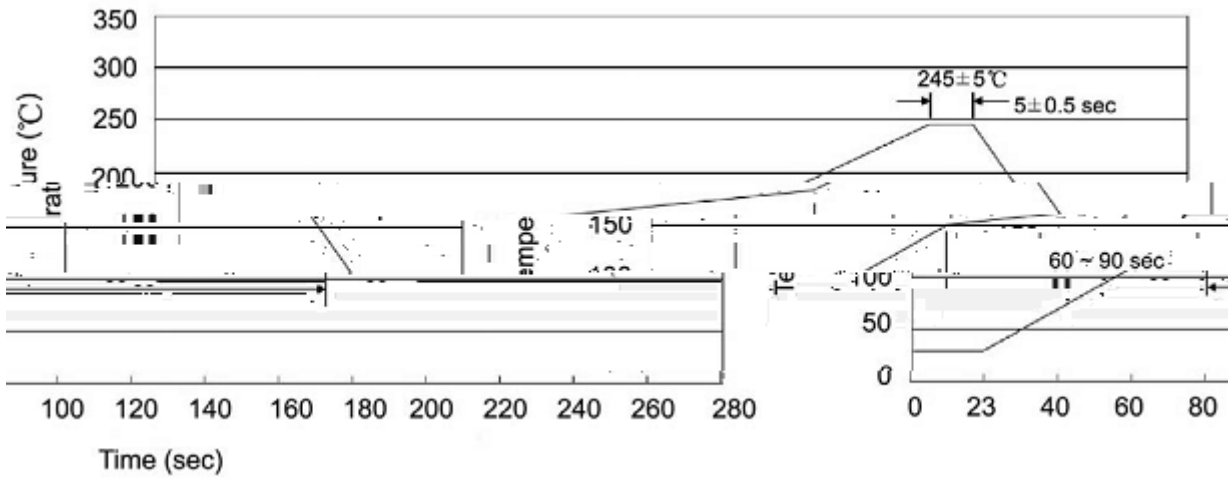
DAO

Note:

H: Company Code

DAO: Product Type Code

( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)



Note:

- |   |       |     |           |          |   |
|---|-------|-----|-----------|----------|---|
| 1 | 25    | 150 | 60        | 90sec;   | 1.Preheating:25~150 , Time:60~90sec.    |
| 2 | 245±5 |     | 5±0.5sec; |          | 2.Peak Temp.:245±5 , Duration:5±0.5sec. |
| 3 |       |     | 2         | 10 /sec. | 3. Cooling Speed: 2~10 /sec.            |

/ Resistance to Soldering Heat Test Conditions

260±5                      10±1 sec.                      Temp.:260±5                      Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type	Units					Dimension (unit mm <sup>3</sup> )		
	Units/Reel	Reels/Inner Box	Units/Inner Box	Inner Boxes/Outer Box	Units/Outer Box	Reel	Inner Box	Outer Box
SOT-23	3,000	10	30,000	6	180,000	7 ×8	180×120×180	390×385×205

/ Notices